2SJ410

Silicon P-Channel MOS FET

HITACHI

ADE-208-539

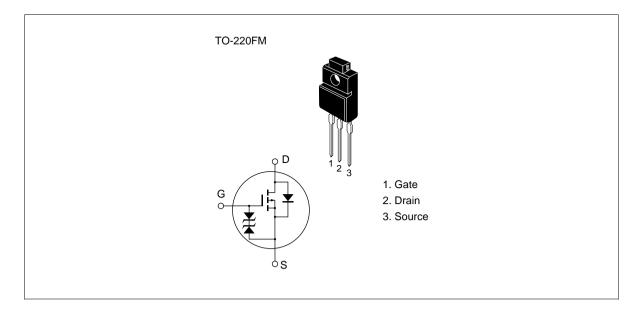
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter and motor driver

Outline





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Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{\scriptscriptstyle DSS}$	-200	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I _D	– 6	A
Drain peak current	l _{D(pulse)} *1	-24	A
Body to drain diode reverse drain current	I _{DR}	-6	A
Channel dissipation	Pch*2	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

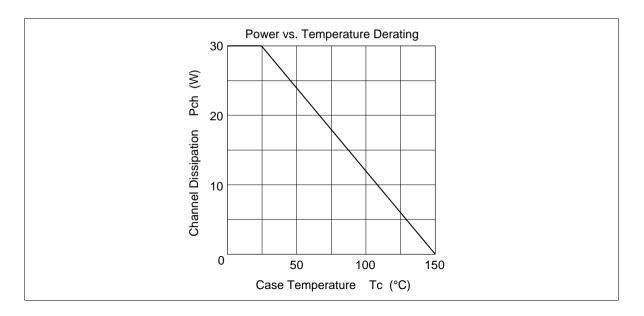
2. Value at Tc = 25°C

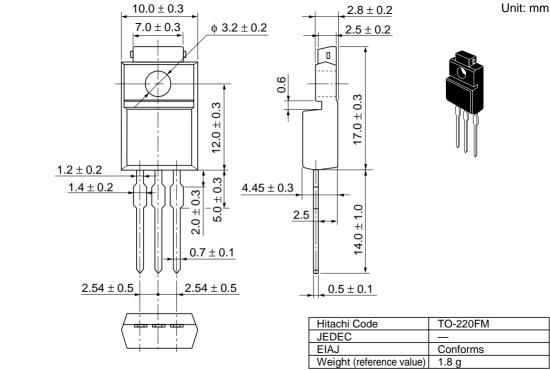
Electrical Characteristics ($Ta = 25^{\circ}C$)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-200	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	-250	μΑ	$V_{DS} = -160 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{\rm GS(off)}$	-2.0	_	-4.0	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	$R_{\scriptscriptstyle DS(on)}$	_	0.7	0.85	Ω	$I_D = -3 A$ $V_{GS} = -10 V^{*1}$
Forward transfer admittance	y _{fs}	2.0	3.2	_	S	$I_D = -3 \text{ A}$ $V_{DS} = -10 \text{ V}^{*1}$
Input capacitance	Ciss	_	900	_	pF	V _{DS} = -10 V
Output capacitance	Coss	_	280	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	65	_	pF	f = 1 MHz
Turn-on delay time	t _{d(on)}	_	18	_	ns	$I_D = -3 \text{ A}$
Rise time	t _r	_	50	_	ns	$V_{GS} = -10 \text{ V}$
Turn-off delay time	t _{d(off)}	_	90	_	ns	$R_L = 6\Omega$
Fall time	t _f	_	40	_	ns	
Body to drain diode forward voltage	V_{DF}		-1.0		V	$I_F = -6 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}		220	_	ns	$I_F = -6 \text{ A}, V_{GS} = 0,$ diF/dt = 50 A/ μ s

Note: 1. Pulse Test

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